

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

2SK3342

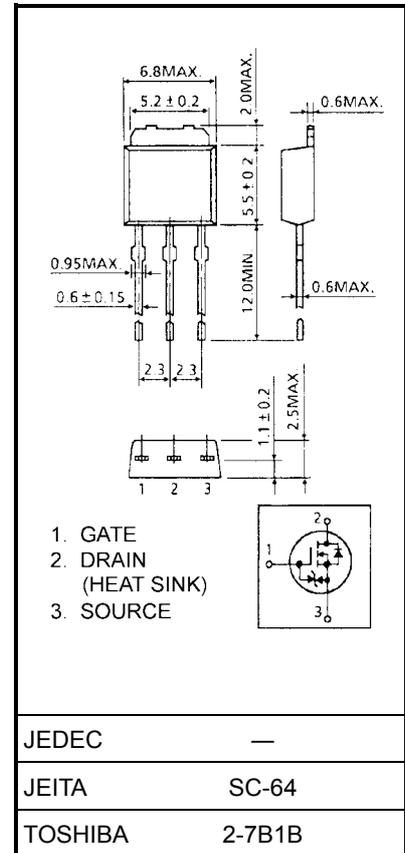
Switching Regulator Applications DC-DC Converter, and Motor Drive Applications

Unit: mm

- Low drain-source ON resistance : $R_{DS(ON)} = 0.8 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 4.5 \text{ S}$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu\text{A}$ (max) ($V_{DS} = 250 \text{ V}$)
- Enhancement-mode : $V_{th} = 1.5 \sim 3.5 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	250	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	250	V
Gate-source voltage		V_{GSS}	± 20	V
Drain current	DC (Note 1)	I_D	4.5	A
	Pulse (Note 1)	I_{DP}	18	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)		P_D	20	W
Single pulse avalanche energy (Note 2)		E_{AS}	51	mJ
Avalanche current		I_{AR}	4.5	A
Repetitive avalanche energy (Note 3)		E_{AR}	2.0	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55~150	$^\circ\text{C}$



Weight: 0.36 g (typ.)

Thermal Characteristics

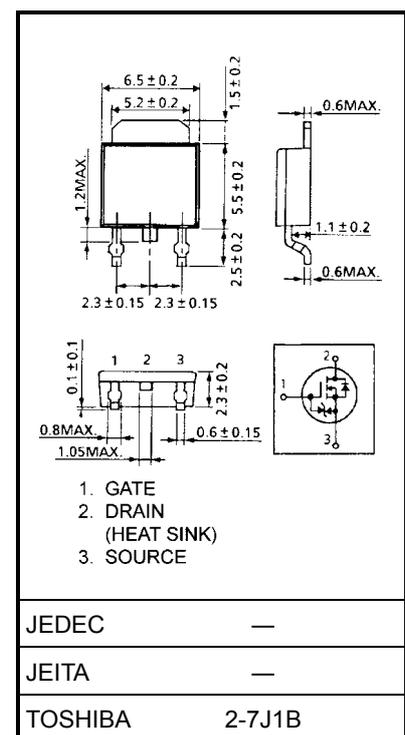
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	6.25	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	125	$^\circ\text{C} / \text{W}$

Note 1: Please use devices on condition that the channel temperature is below 150°C .

Note 2: $V_{DD} = 50 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 4.28 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 4.5 \text{ A}$

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.36 g (typ.)

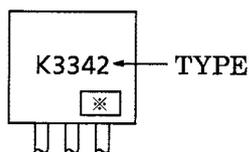
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cut-off current		I_{DSS}	$V_{DS} = 250\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	250	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	1.5	—	3.5	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 2.5\text{ A}$	—	0.8	1.0	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 2.5\text{ A}$	2.0	4.5	—	S
Input capacitance		C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	440	—	pF
Reverse transfer capacitance		C_{rss}		—	35	—	
Output capacitance		C_{oss}		—	120	—	
Switching time	Rise time	t_r		—	15	—	ns
	Turn-on time	t_{on}		—	20	—	
	Fall time	t_f		—	15	—	
	Turn-off time	t_{off}		Duty $\leq 1\%$, $t_w = 10\mu\text{s}$	—	60	
Total gate charge (Gate-source plus gate-drain)		Q_g	$V_{DD} \approx 100\text{ V}, V_{GS} = 10\text{ V}, I_D = 4.5\text{ A}$	—	10	—	nC
Gate-source charge		Q_{gs}		—	6	—	
Gate-drain ("miller") charge		Q_{gd}		—	4	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	4.5	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	18	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 4.5\text{ A}, V_{GS} = 0\text{ V}$	—	—	-2.0	V
Reverse recovery time	t_{rr}	$I_{DR} = 4.5\text{ A}, V_{GS} = 0\text{ V}$	—	110	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100\text{ A} / \mu\text{s}$	—	0.47	—	μC

Marking



※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)

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